

a second plate disposed adjacent to said first plate, wherein said second plate defines a second internal cavity configured to receive a second gas through a first passage into said second internal cavity at a first temperature and to emit said gas from said second internal cavity at a second temperature through a second passage.

3. (Allowed) The system of Claim 2, wherein said second passage comprise a plurality of holes defined on a surface of said first and said second plates.

4. (Allowed) The system of Claim 2, wherein said first plate and said second plate comprise a heat source for heating said plate to a preselected temperature.

5. (Allowed) The system of Claim 2, wherein said first gas is taken from the group consisting of N₂, He, H₂, O₂, Ar and gas mixtures containing He, H₂, O₂, Ar and N₂.

6. (Allowed) The system of Claim 2, wherein said internal cavity further comprises a buffer to disperse said first gas throughout said internal cavity.

Please cancel Claim 7.

8. (Allowed) A system for wafer processing comprising:
a chamber; and
at least one heatable plate positionable within said chamber, including:
an internal cavity defining an internal wall and configured to receive a gas;
means for heating said internal wall to a preselected temperature; and
an outlet portion defining a plurality of holes for emitting said gas; said at least one heatable plate including a first heatable plate and a second heatable plate disposed having adjacent surfaces configured to receive a wafer therebetween.

9. (Allowed) The system of Claim 8, wherein said gas is taken from the group consisting of He, H₂, O₂, Ar, N₂ and gas mixtures containing He, H₂, O₂, Ar, and N₂.

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